

FEATURES

- Surface mount package ideally suited for automatic insertion.
- Very low leakage current. 2pA typical at VR=75V.
- Low capacitance. 4pF max at VR=0V, f=1MHz
- Lead free in compliance with EU RoHS 2.0
- Green molding compound as per IEC 61249 standard

MECHANICAL DATA

- Case : SOT-323 plastic
- Terminals : Solderable per MIL-STD-750, Method 2026
- Approx weight : 0.00018 ounces, 0.005 grams

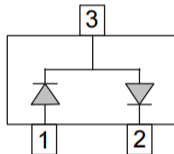


FIG. 17(TOP VIEW)

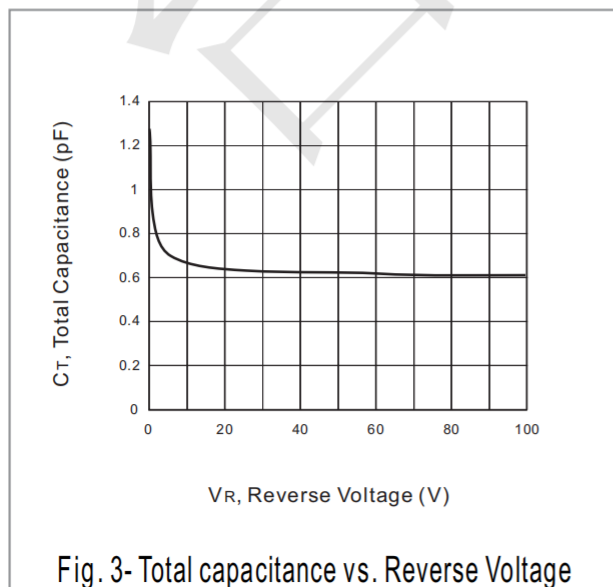
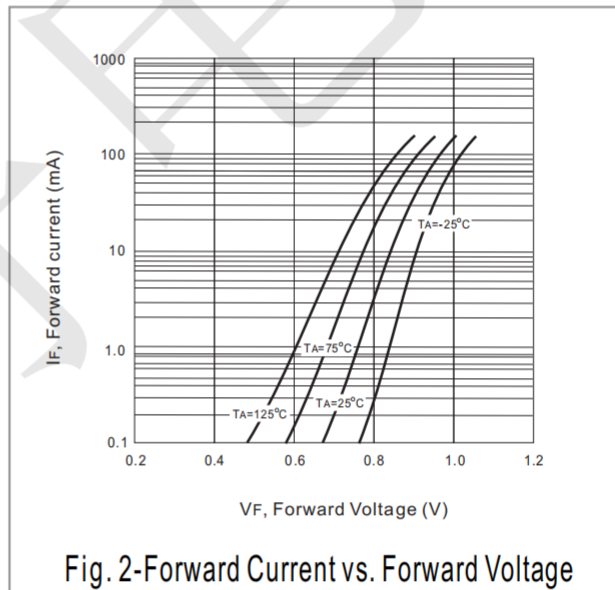
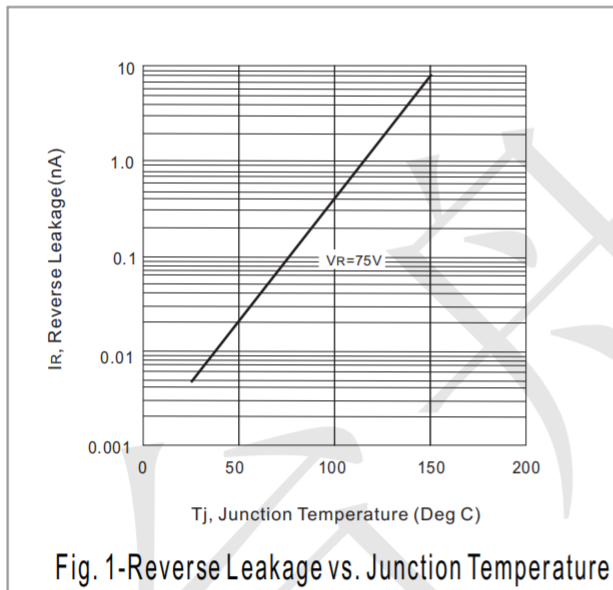
MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Parameter	Symbol		Unit
Reverse voltage	V_R	75	V
Peak reverse voltage	V_{RM}	100	V
Continuous forward current	I_F	0.2	A
Non-repetitive peak forward surge current at $t=1\mu s$	I_{FSM}	4	A
Power dissipation (Note 1)	P_{TOT}	200	mW
Thermal resistance, junction to ambient (Note 1)	$R_{\theta JA}$	625	$^{\circ}C/W$
Junction temperature range	T_J	-55 to +150	$^{\circ}C$
Storage temperature range	T_{STG}	-55 to +150	$^{\circ}C$
Circuit figure	-	Common Cathode	Series -

ELECTRICAL CHARACTERISTICS (each diode) ($T_A=25^{\circ}\text{C}$, unless otherwise noted)

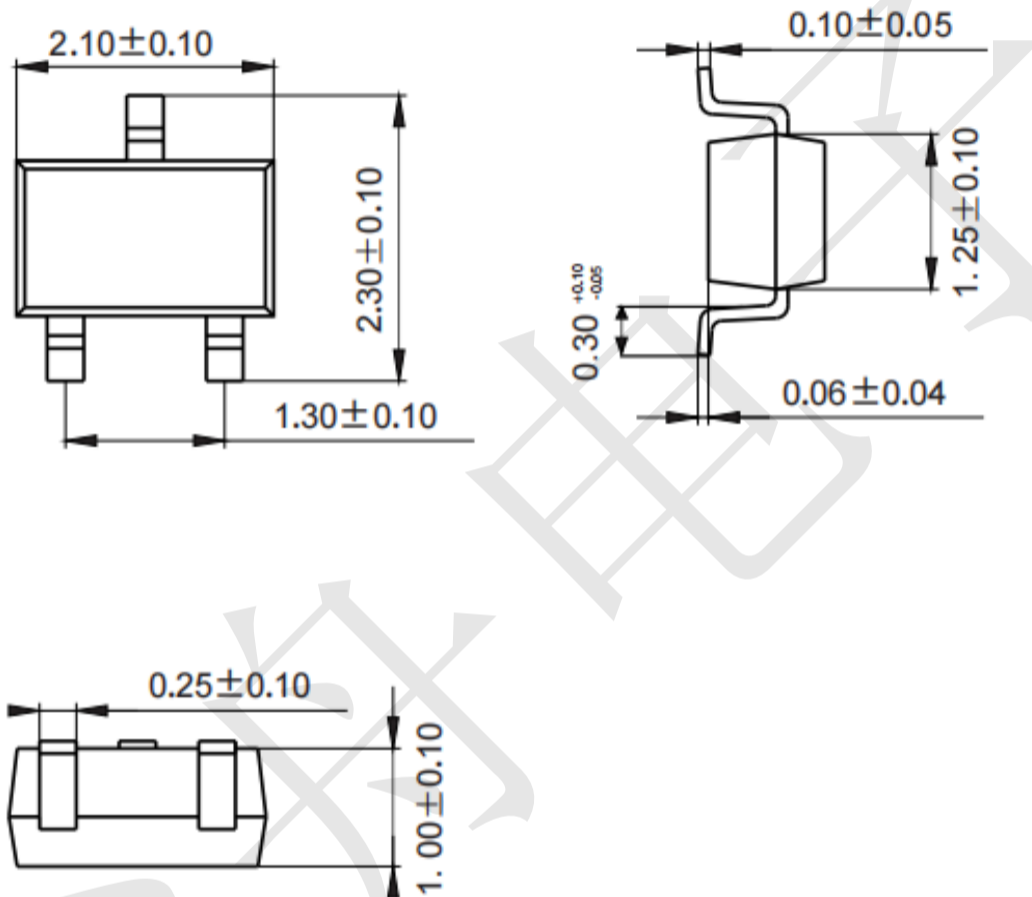
Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Units
Reverse Breakdown Voltage	$V_{(BR)}$	$I_R=100\mu\text{A}$	75	-	-	V
Reverse Current	I_R	$V_R=75\text{V}$ $V_R=75\text{V}, T_J=150^{\circ}\text{C}$	-	0.0028	580	nA
Forward Voltage	V_F	$I_F=1\text{mA}$ $I_F=10\text{mA}$ $I_F=50\text{mA}$ $I_F=150\text{mA}$	-	-	0.9 1 1.1 1.25	V
Total Capacitance	C_T	$V_R=0\text{V}, f=1\text{MHz}$	-	-	2	pF
Reverse Recovery Time	T_{RR}	$I_F=I_R=10\text{mA}, R_L=100\Omega$	-	-	3	μs

CHARACTERISTIC CURVES (each diode)



Package Outline Dimensions (unit:mm)

SOT-323



Mounting Pad Layout (unit: mm)

